

F/G. 1 PRIOR ART

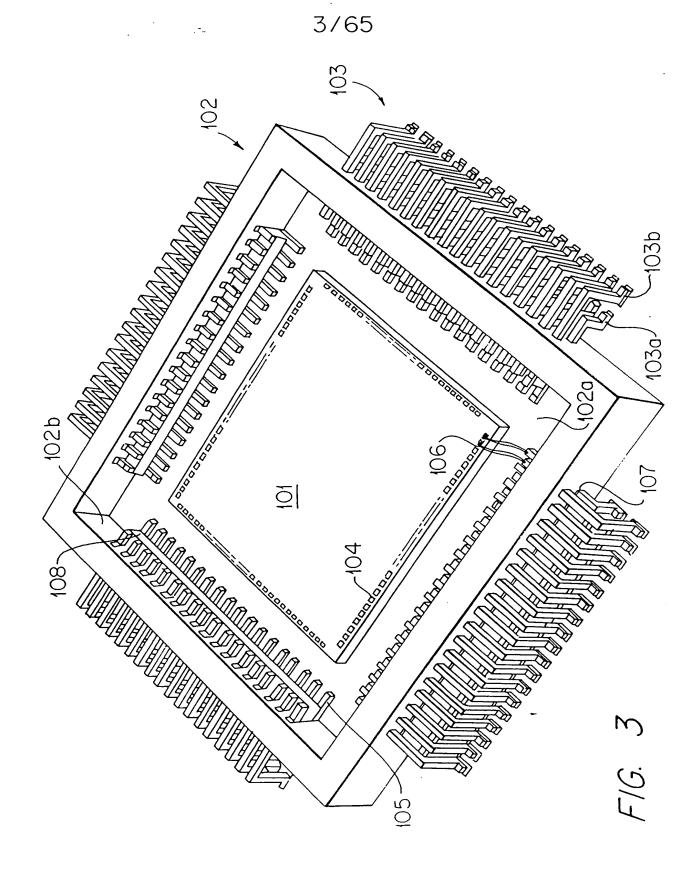
## THROUGH HOLE PACKAGE

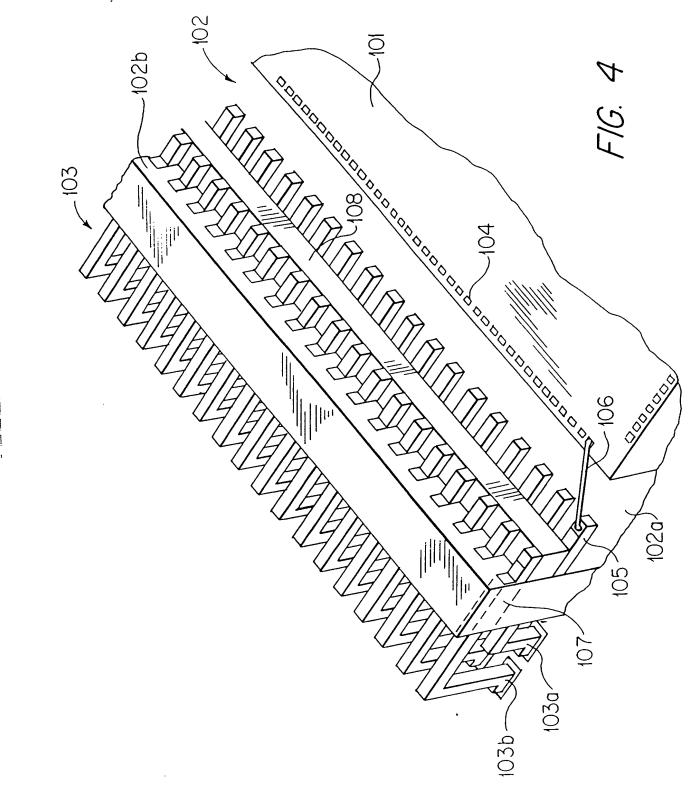
	DIP (DUAL IN-LINE PACKAGE)
THE REPORT OF THE PARTY OF THE	SH-DIP (SHRINK DIP)
	SK-DIP DL-DIP (SKINNY DIP, SLIM DIP)
	SIP (SINGLE IN-LINE PACKAGE)
	ZIP (ZIG-ZAG IN-LINE PACKAGE)
Son Maria La	PGA (PIN GRID ARRAY)

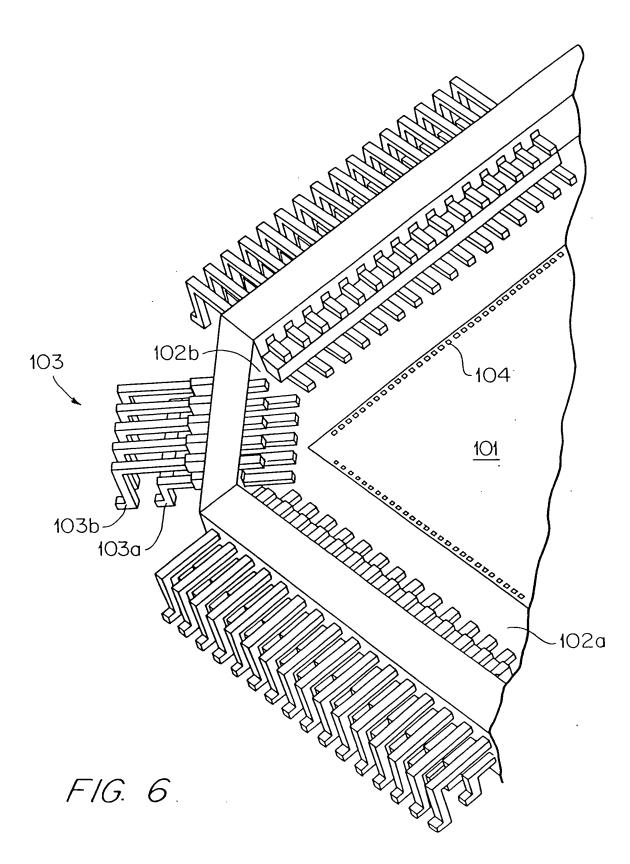
## SURFACE MOUNTED PACKAGE

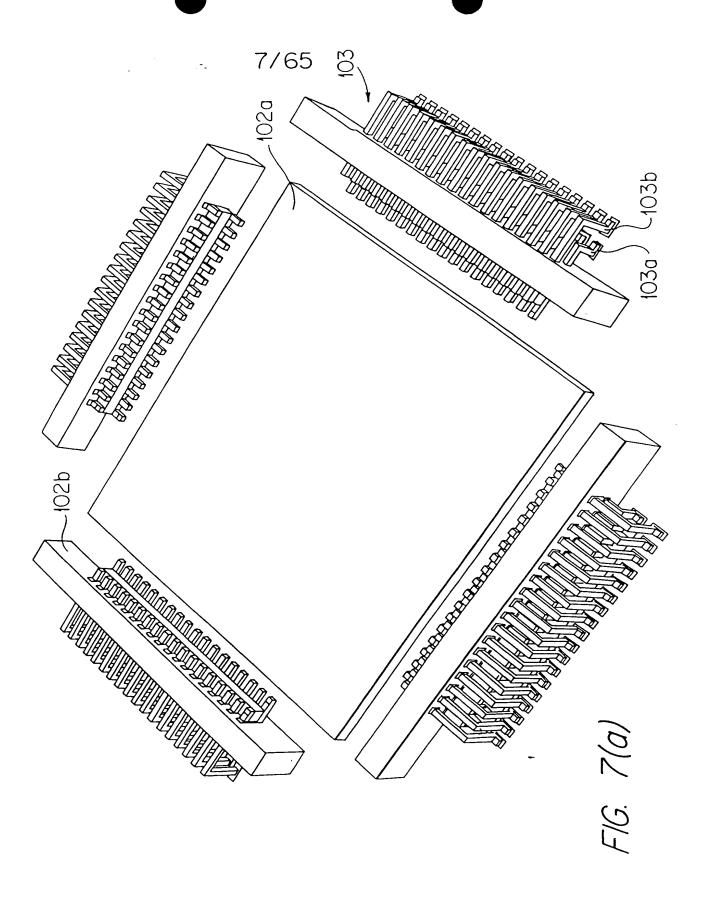
TO TOTAL TOT	SO OR SOP (SMALL OUT- LINE PACKAGE)
Some division of the second	QFP (QUAD FLAT PACKAGE)
	LCC (LEADLESS CHIP CARRIER)
	PLCC SOJ (PLASTIC LEADED CHIP CARRIER WITH BUTT LEADS)

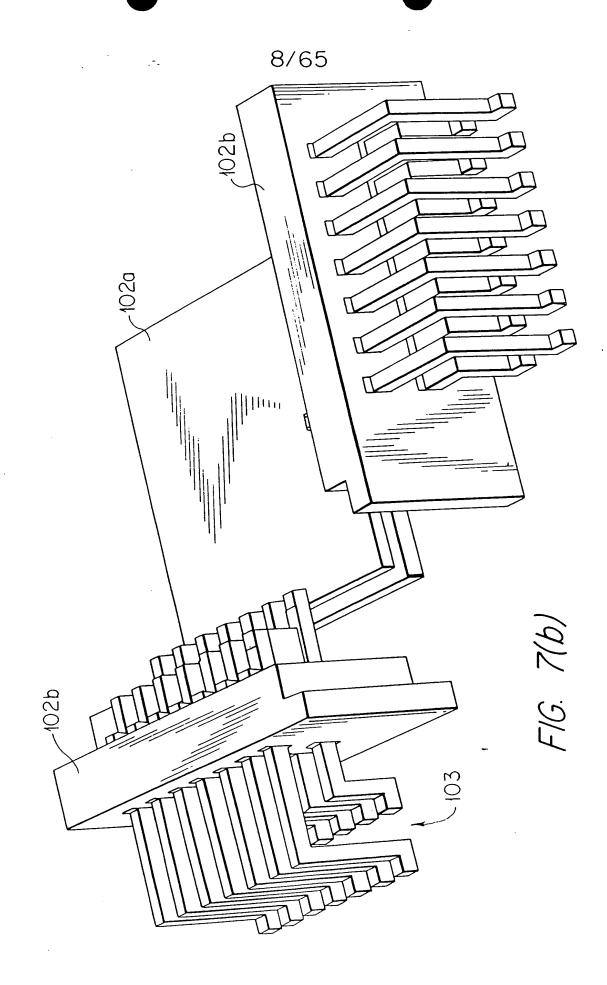
F1G. 2

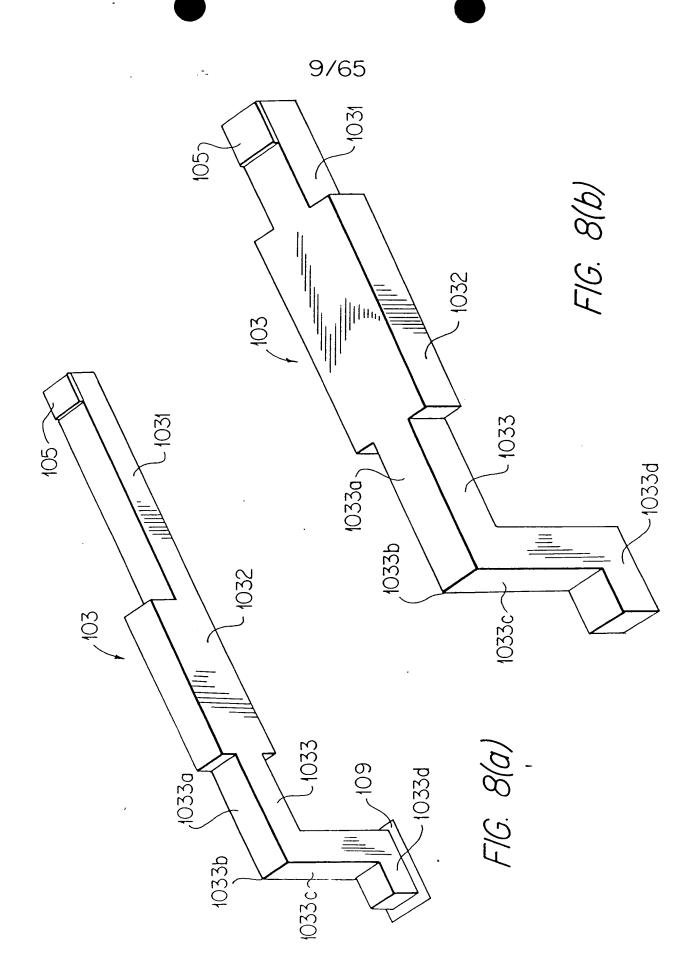


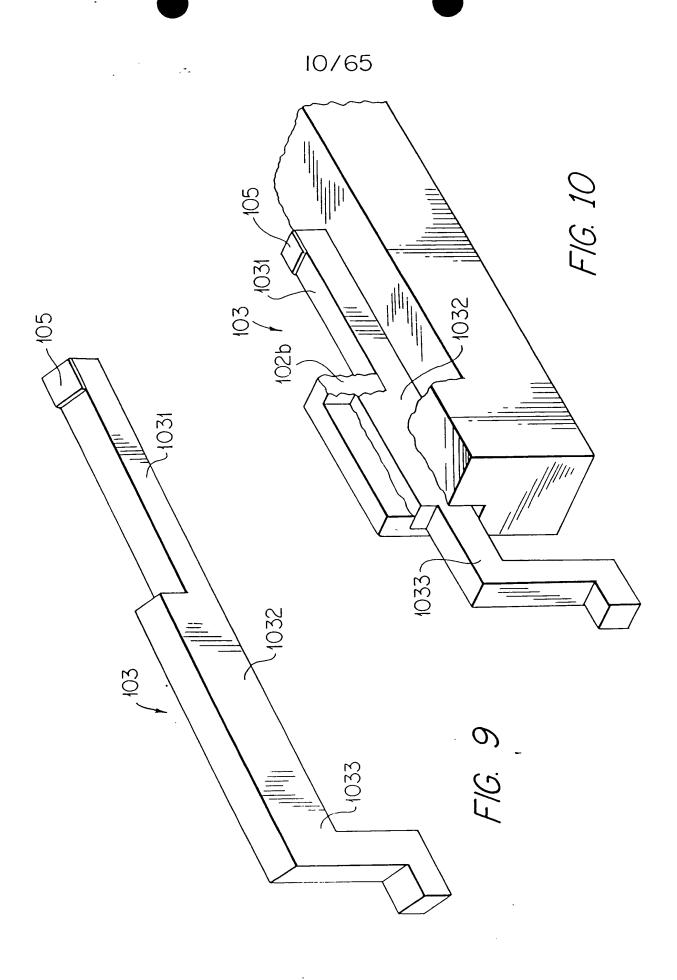


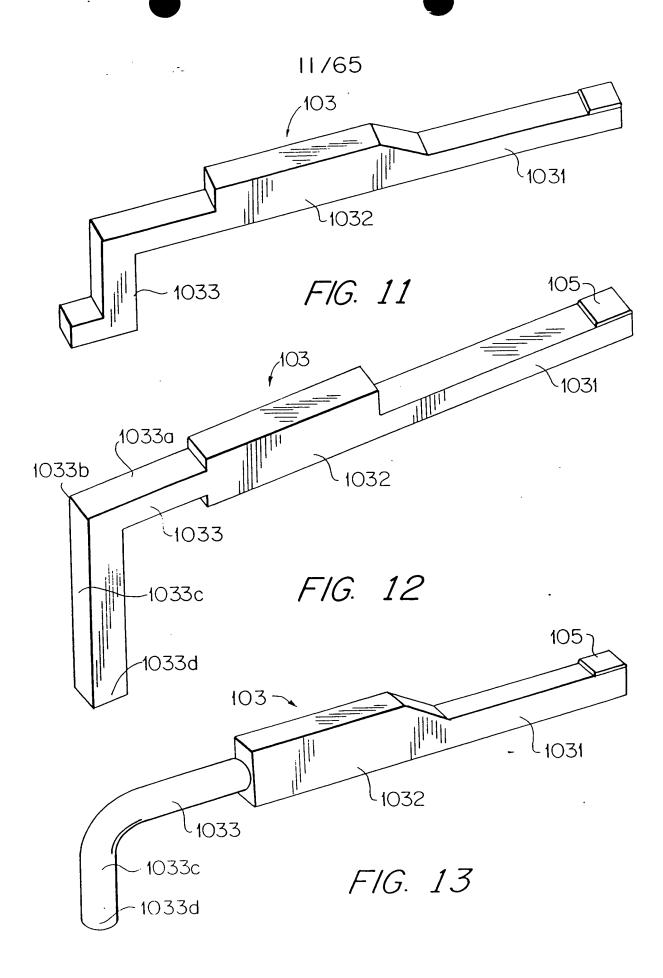


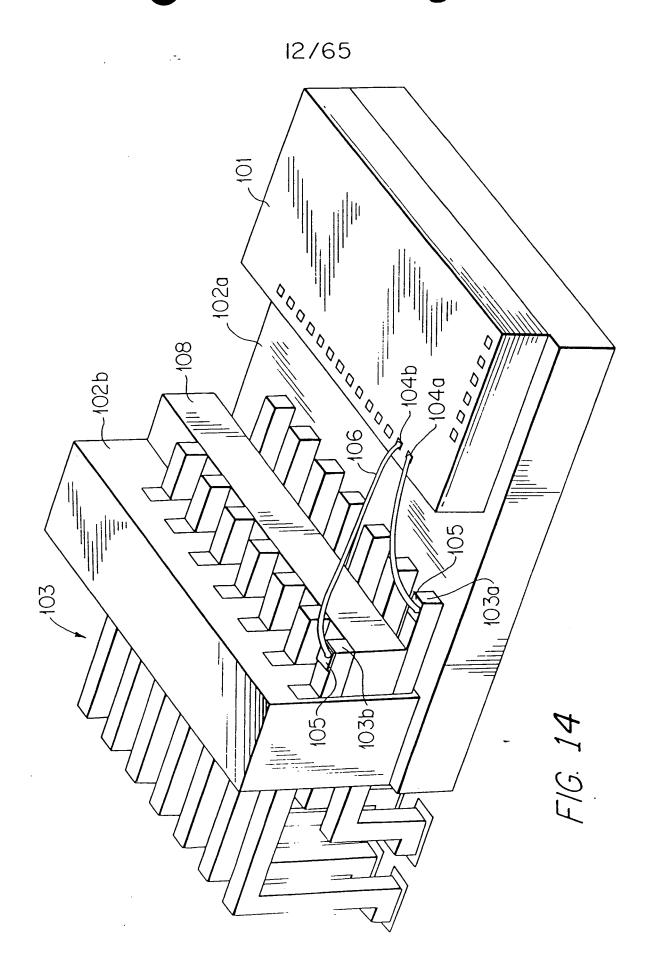


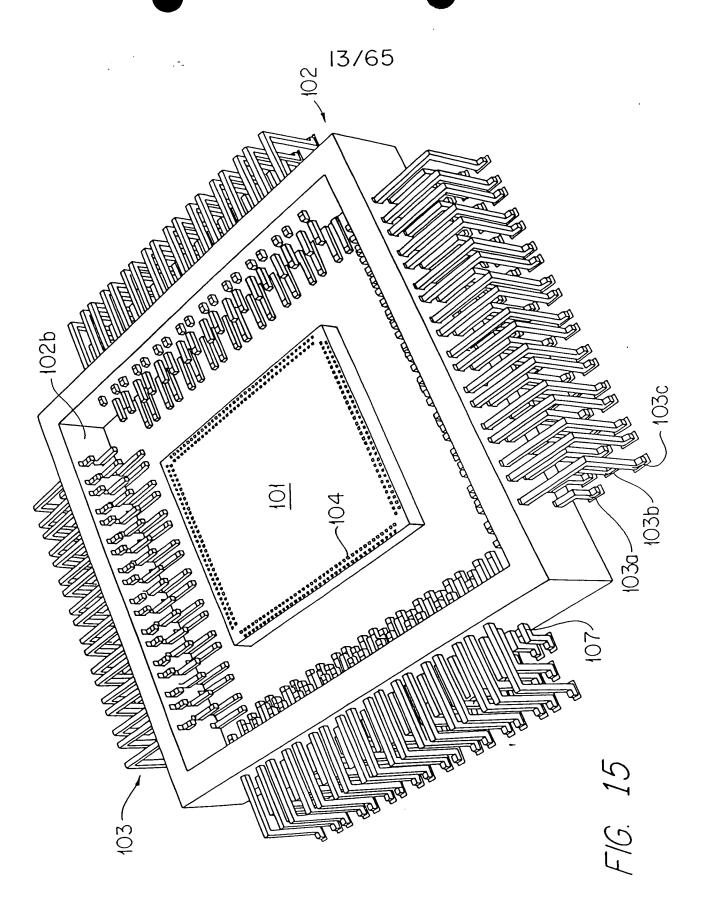




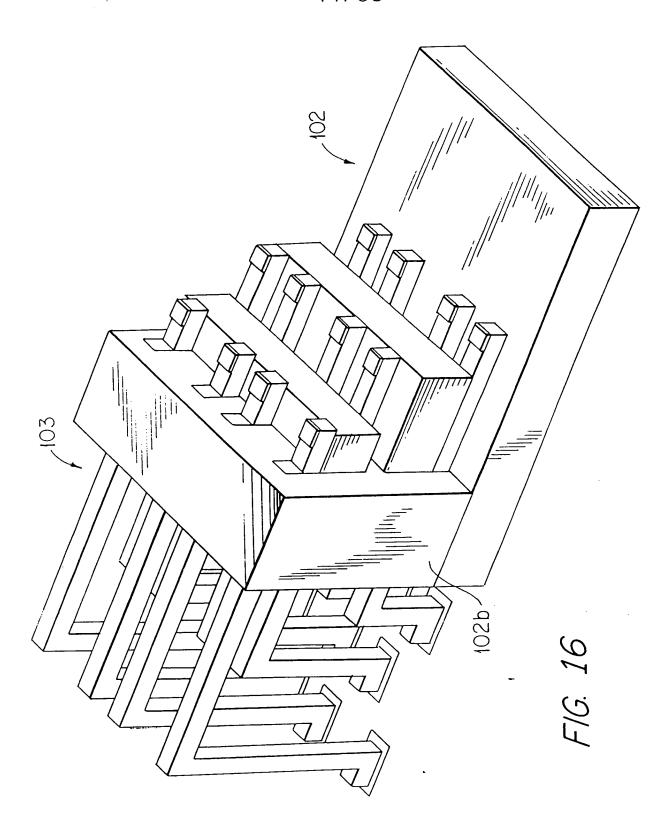


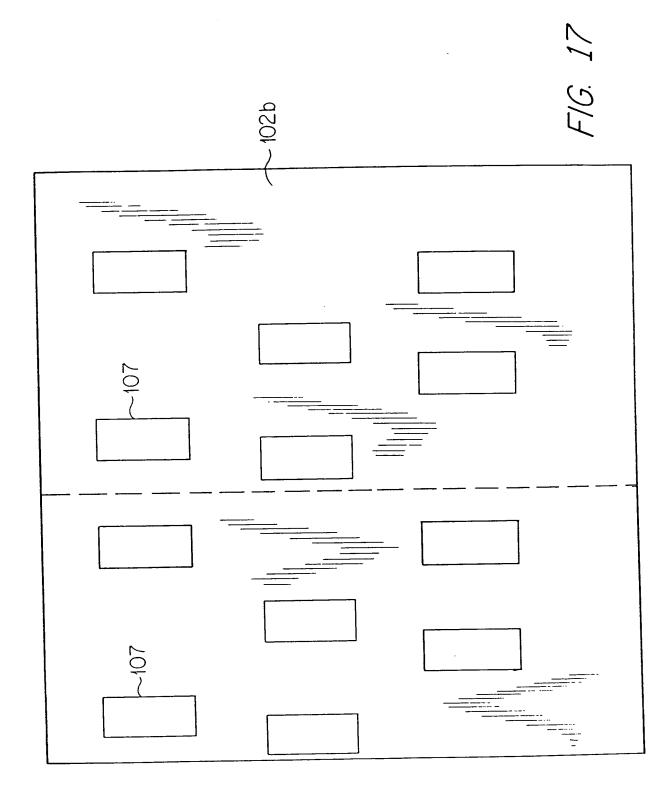




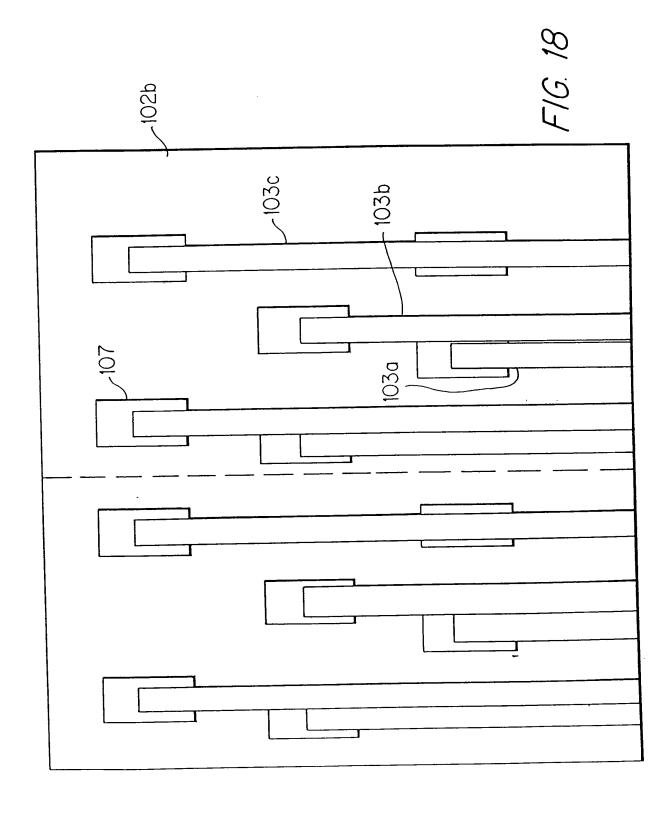


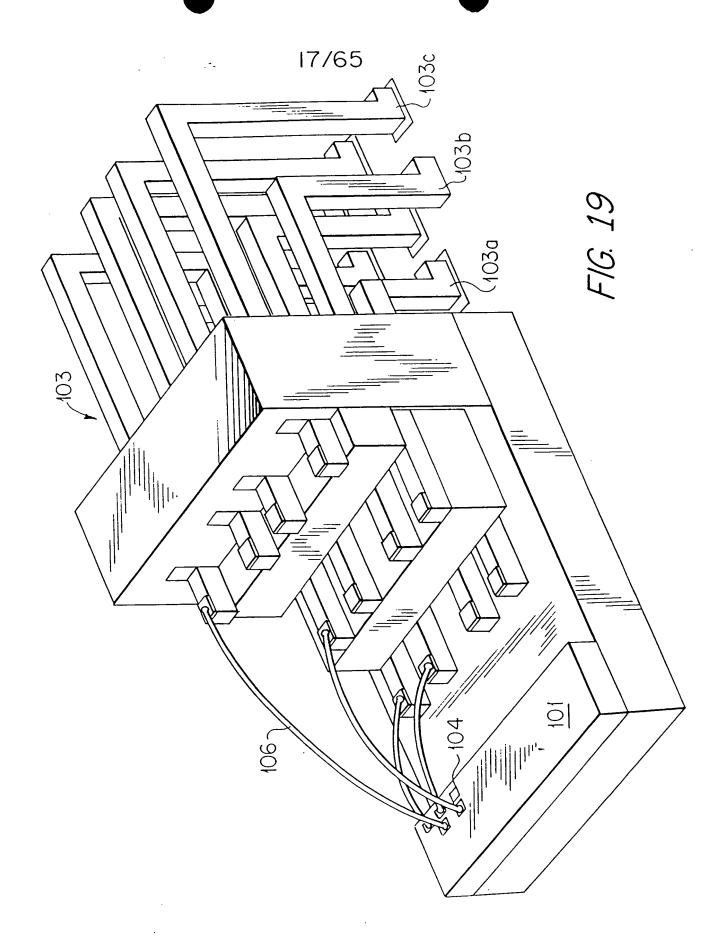
14/65

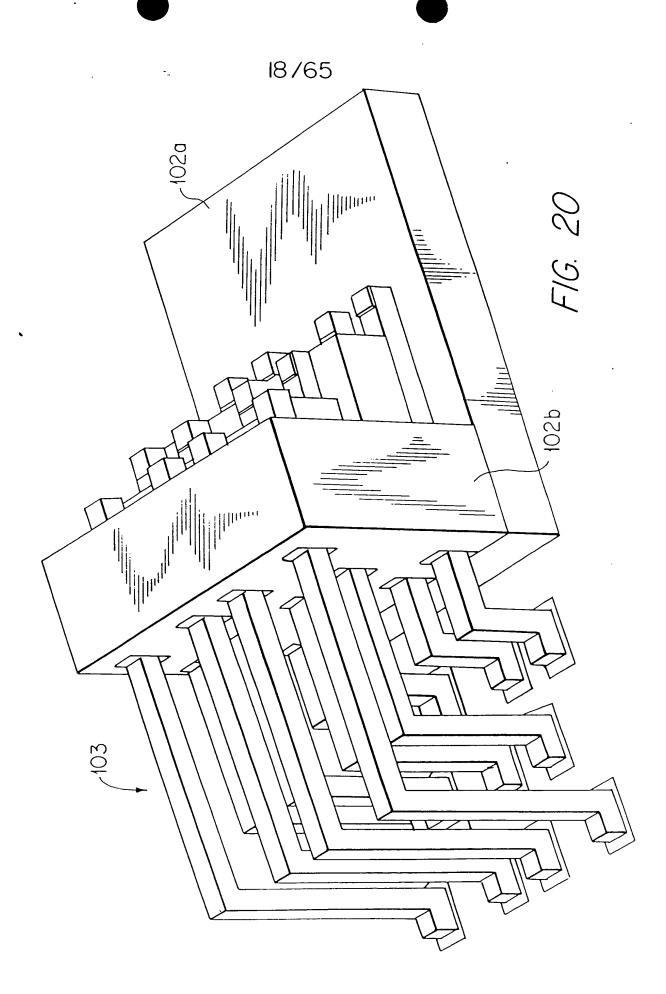


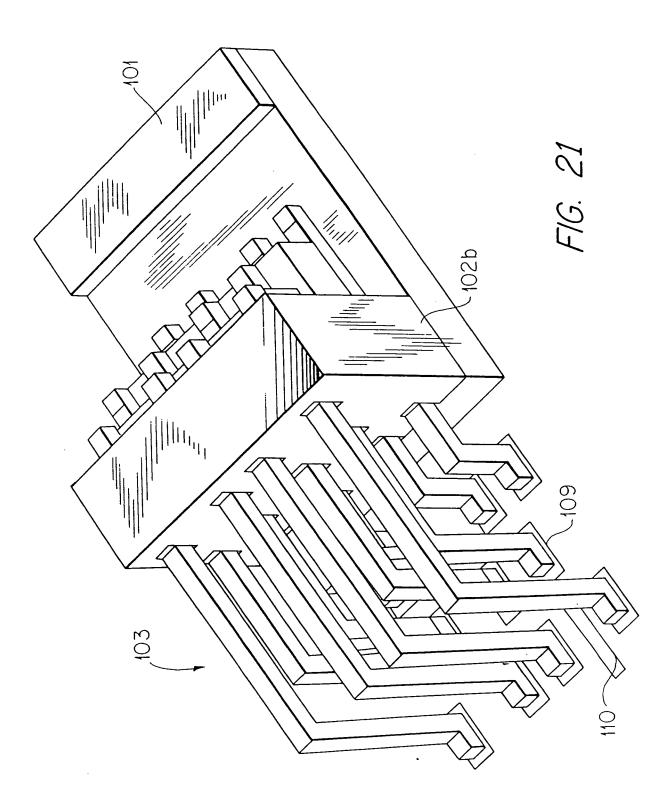


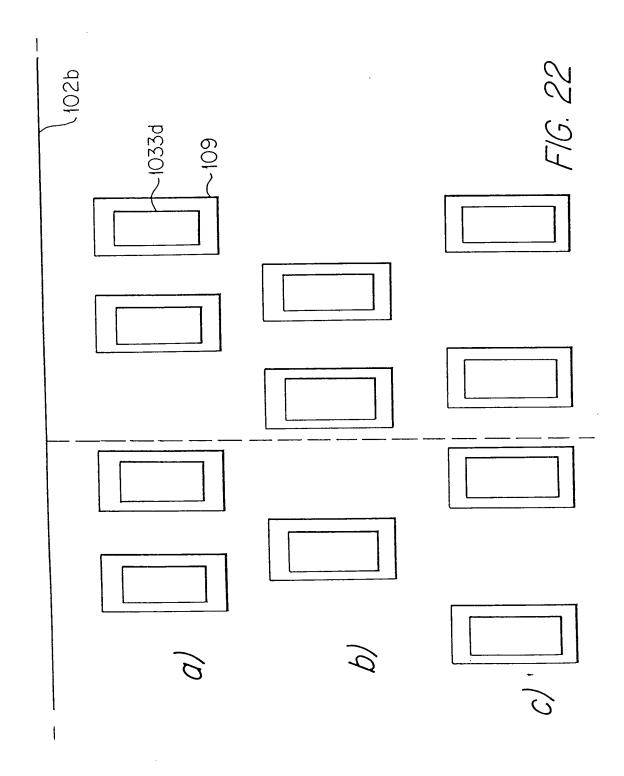
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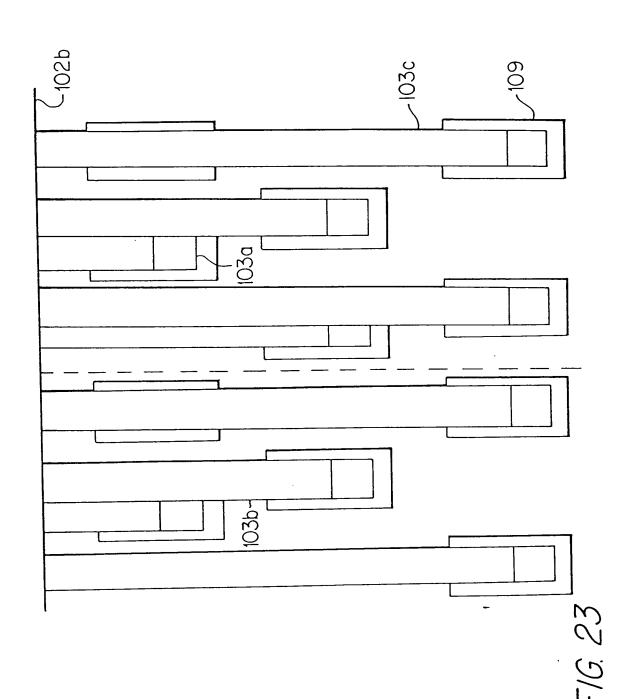


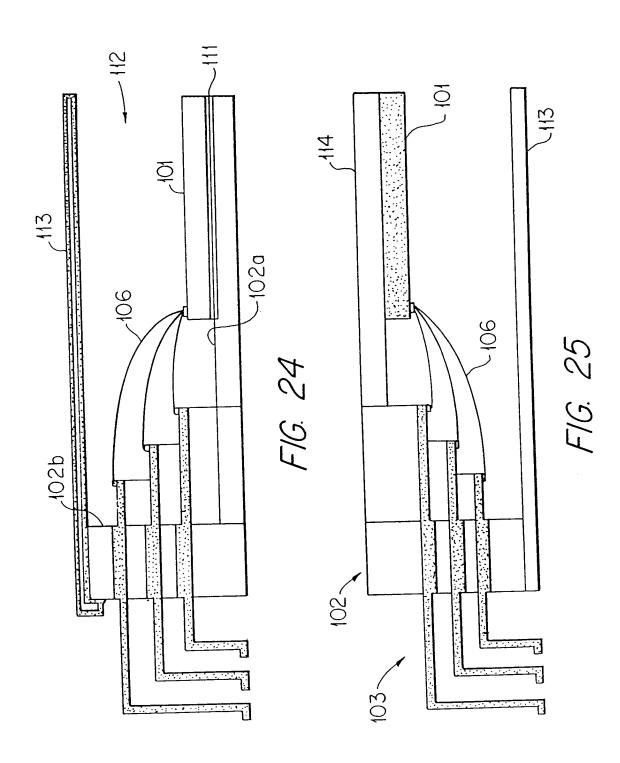












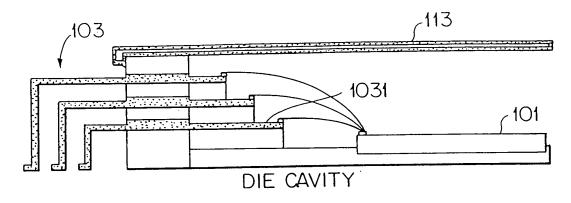


FIG. 26

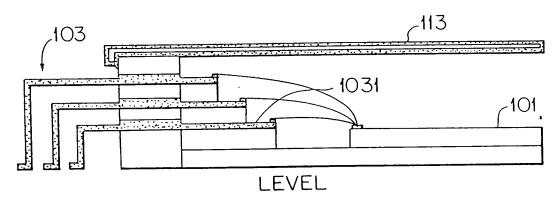


FIG. 27

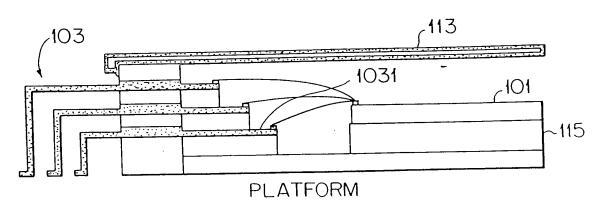
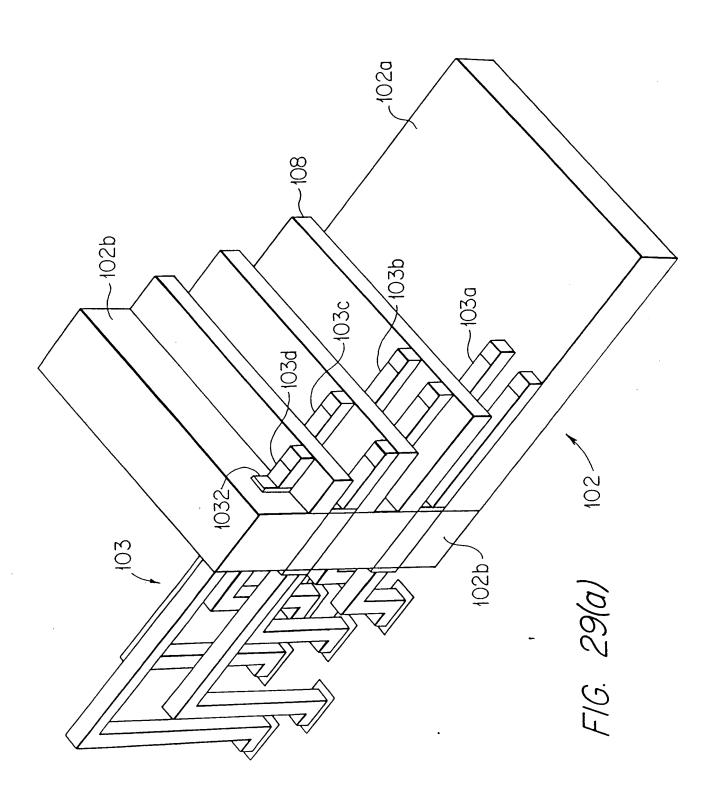
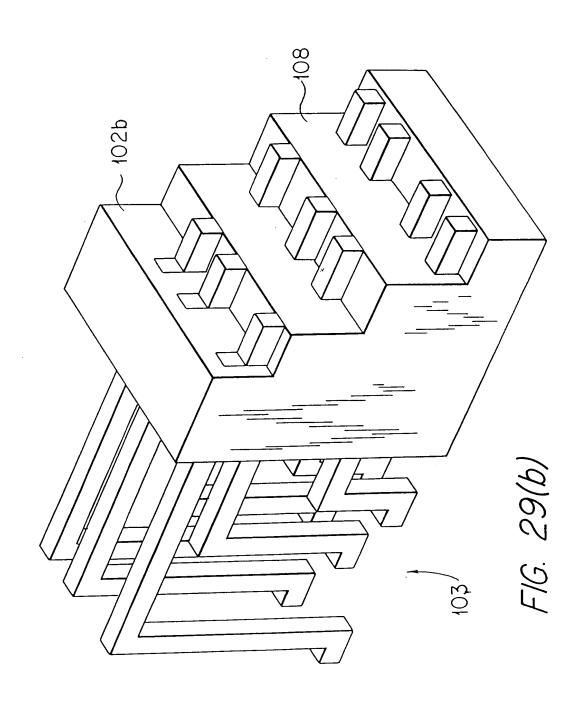
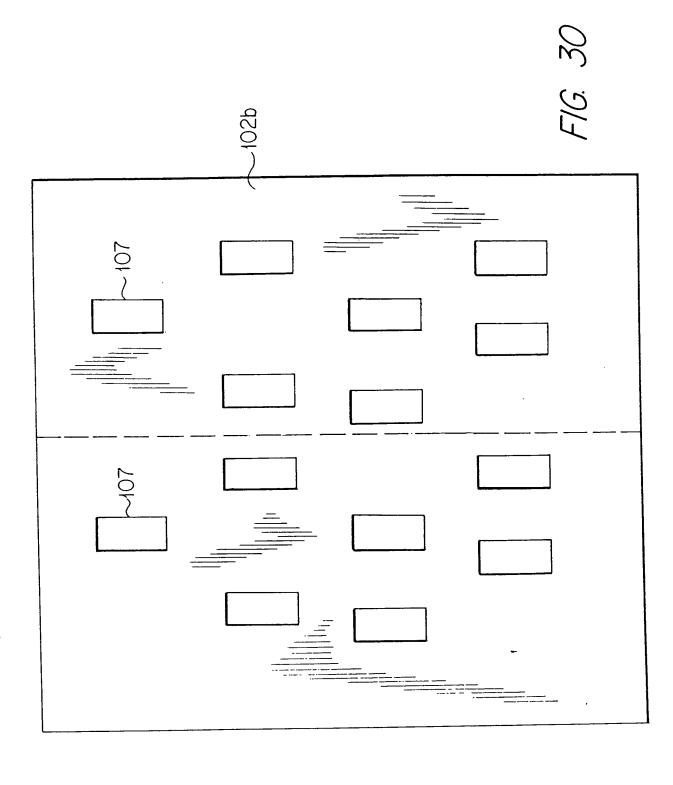


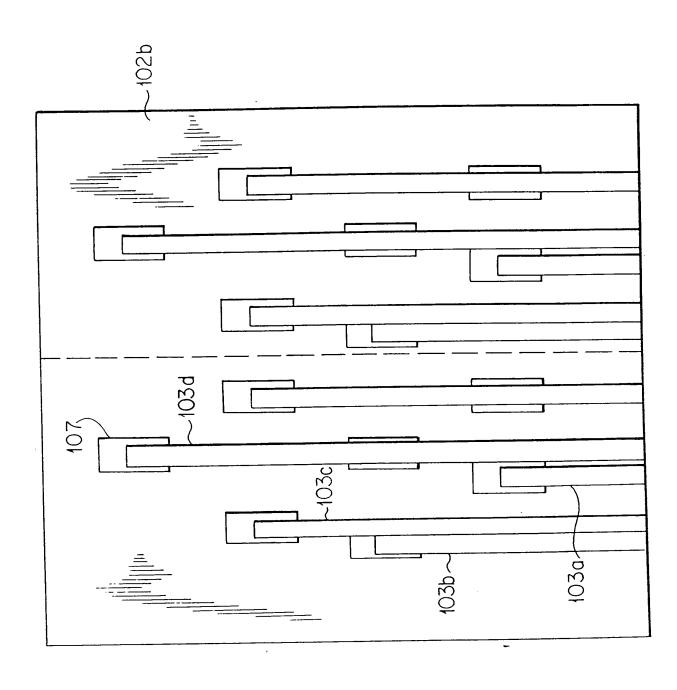
FIG. 28



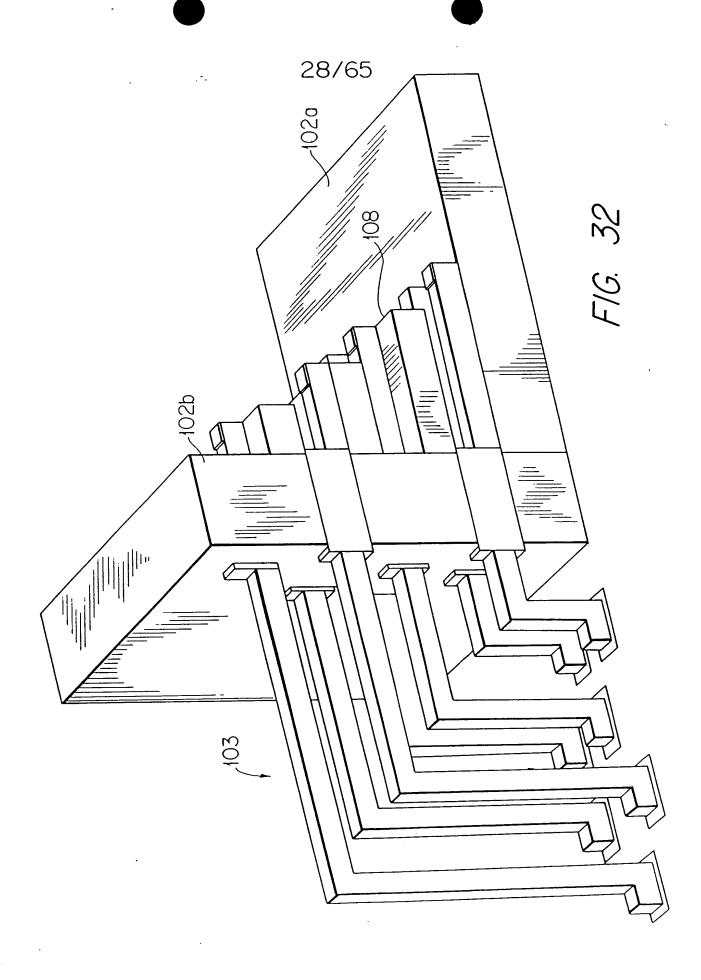


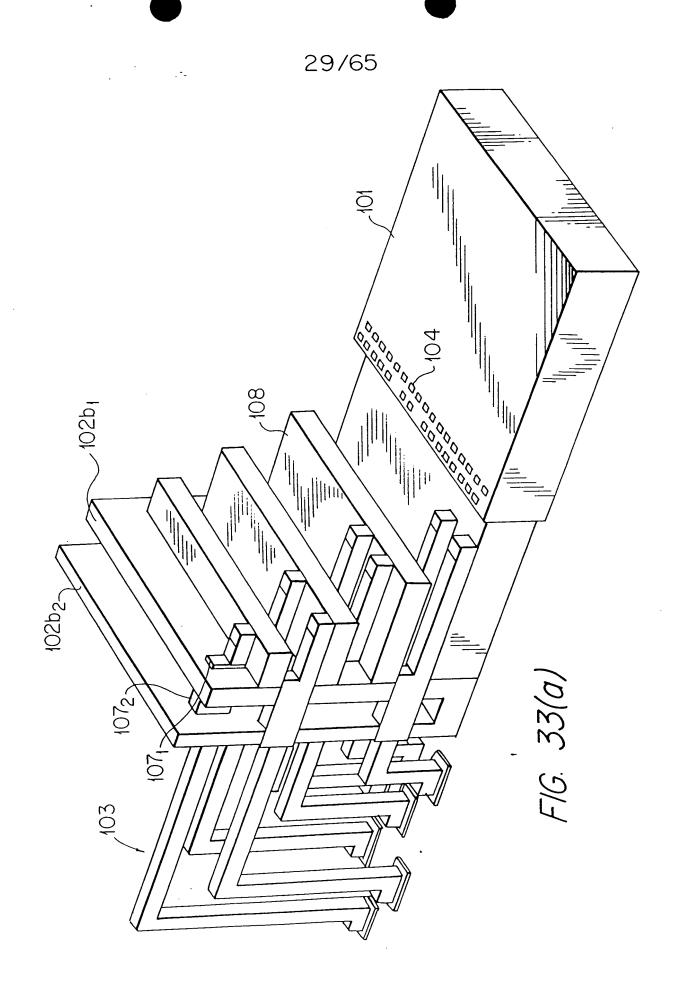


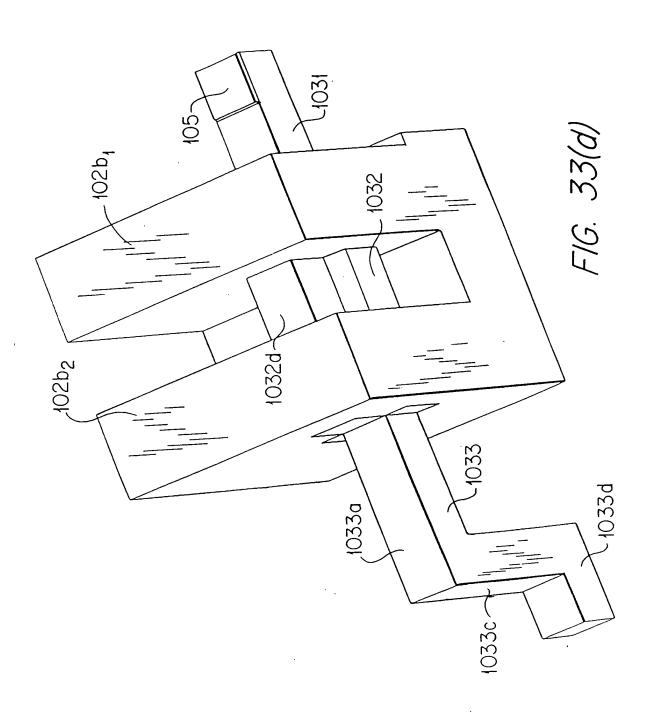


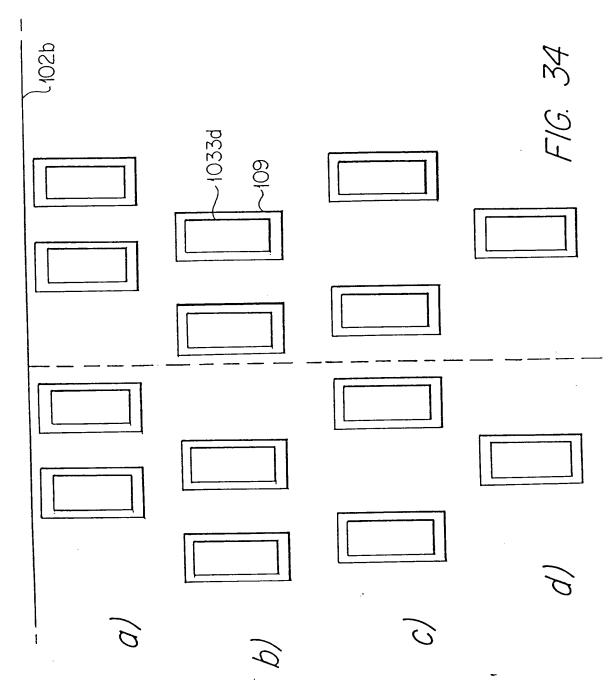


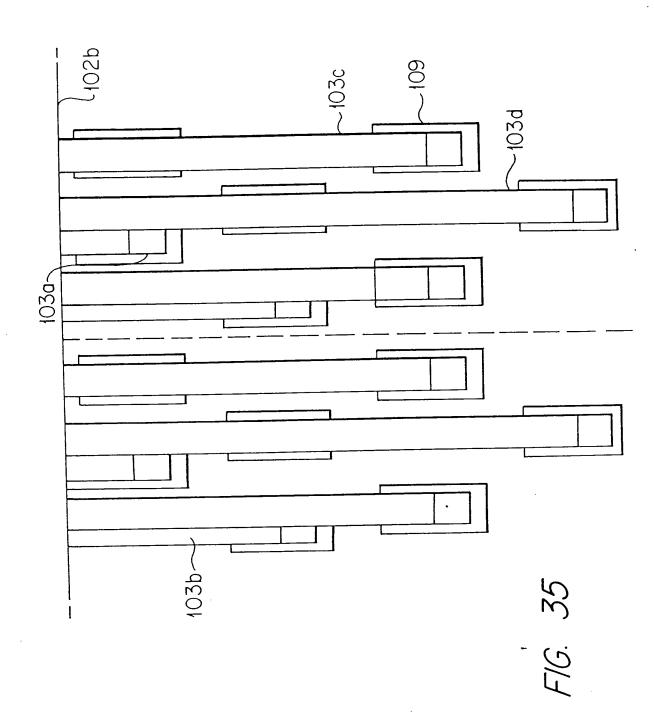
F1G. 3.

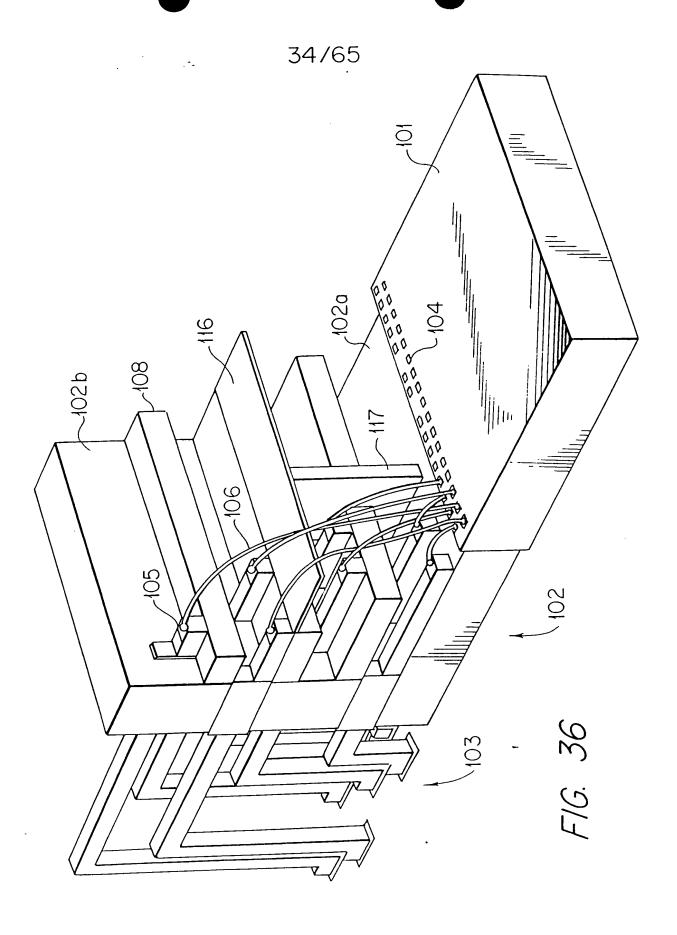


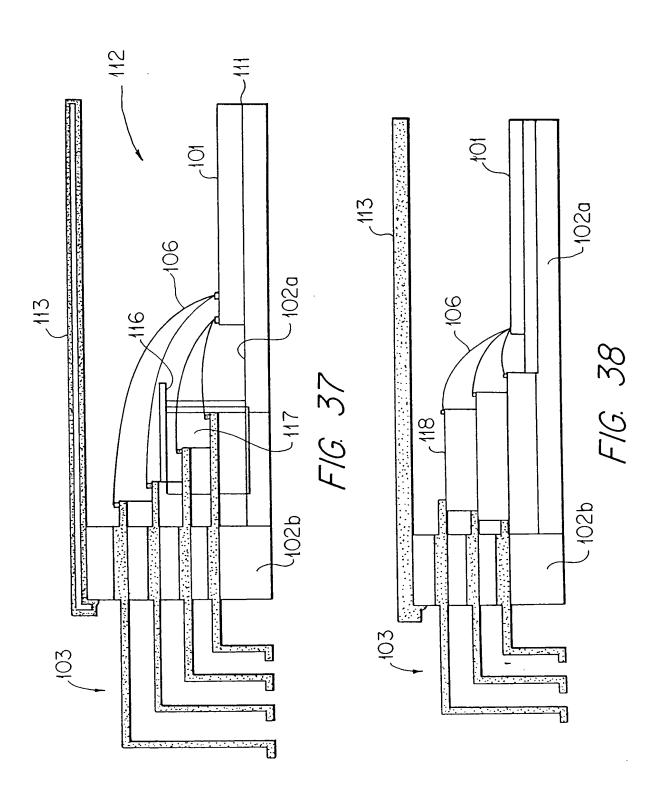


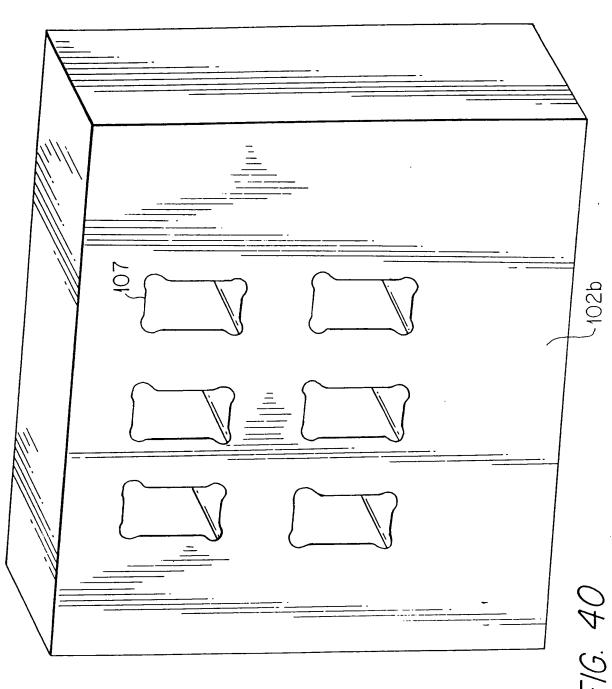


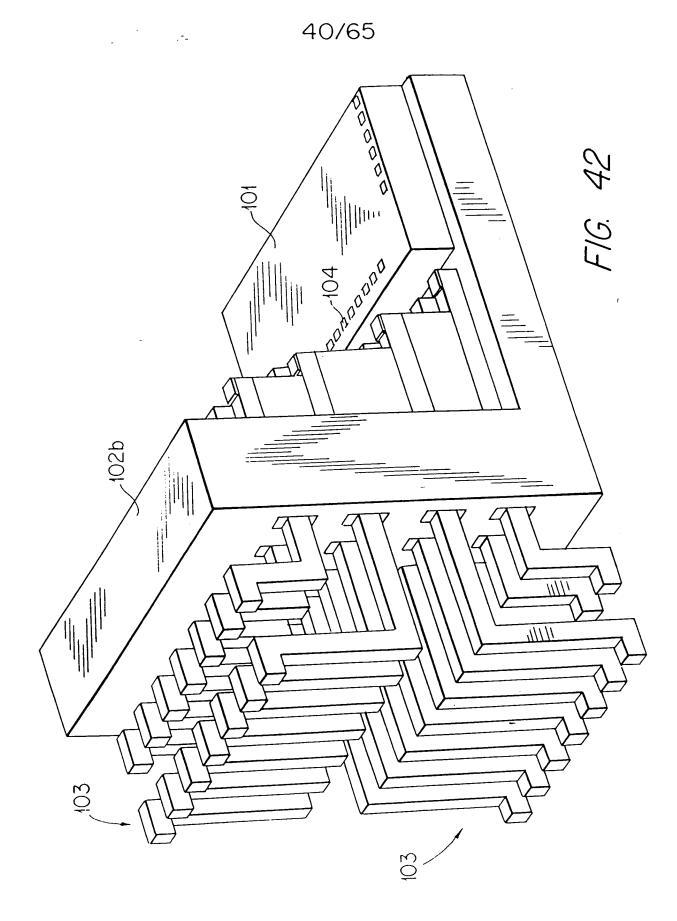


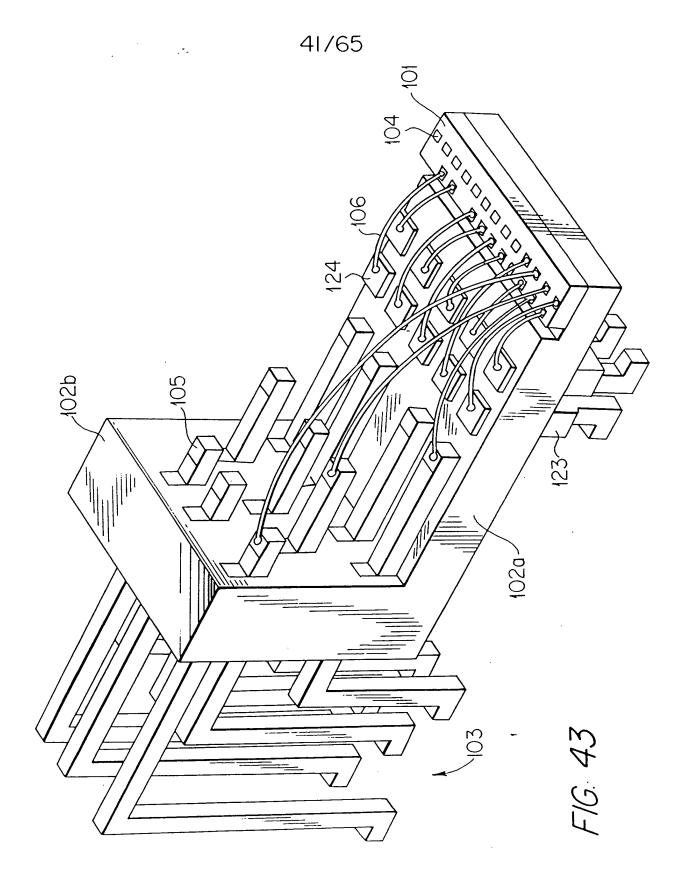












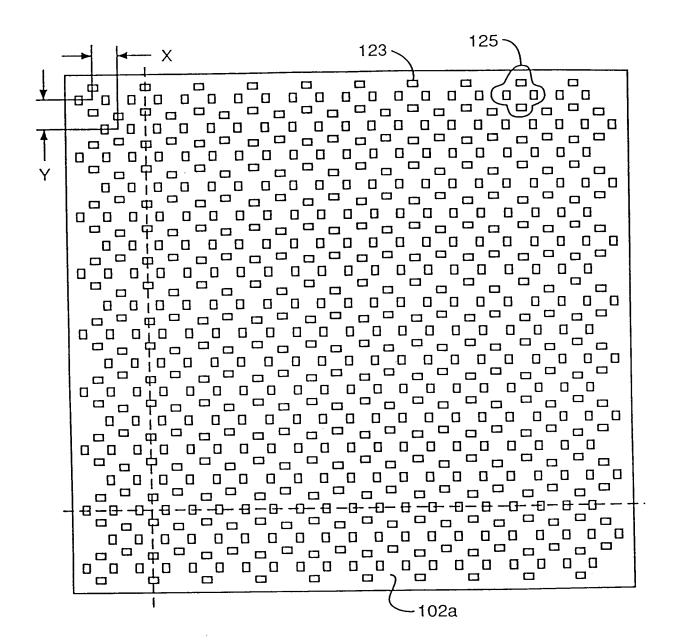
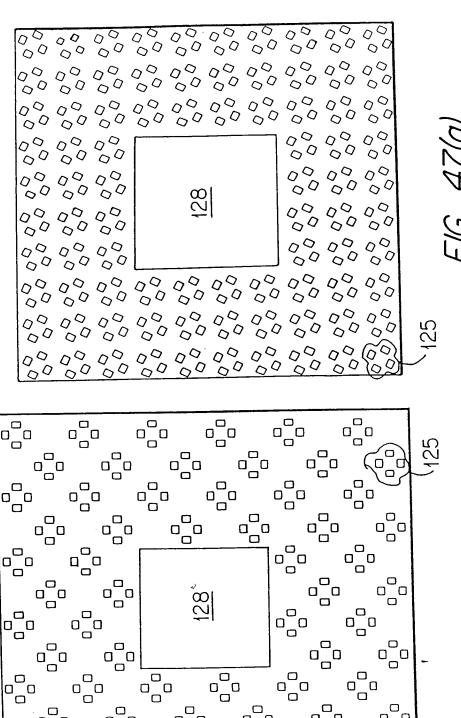


FIG. 44

FIG. 45



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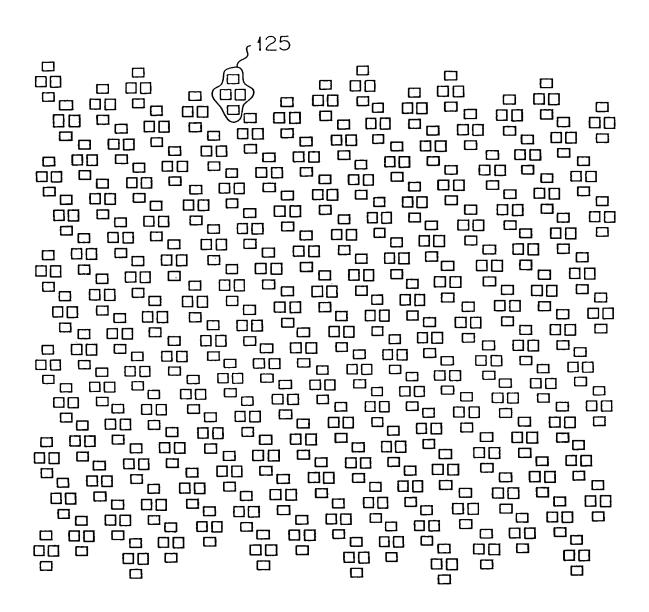
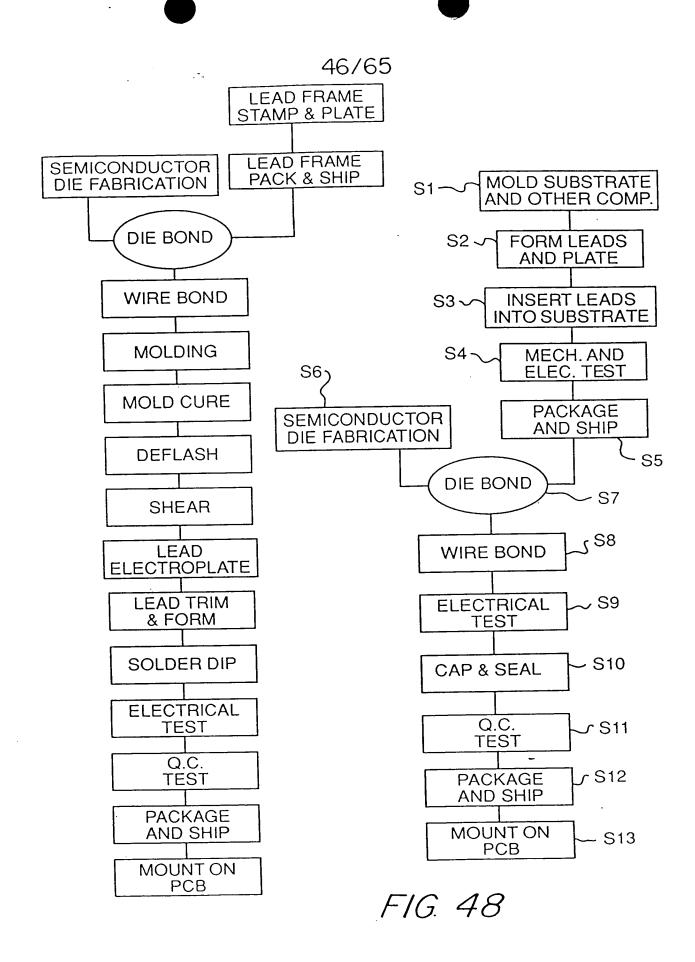
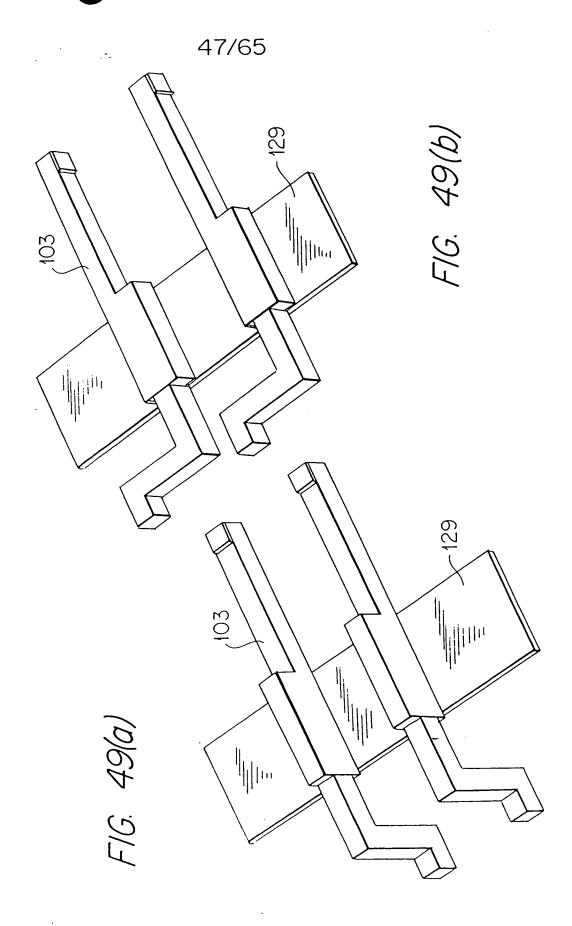
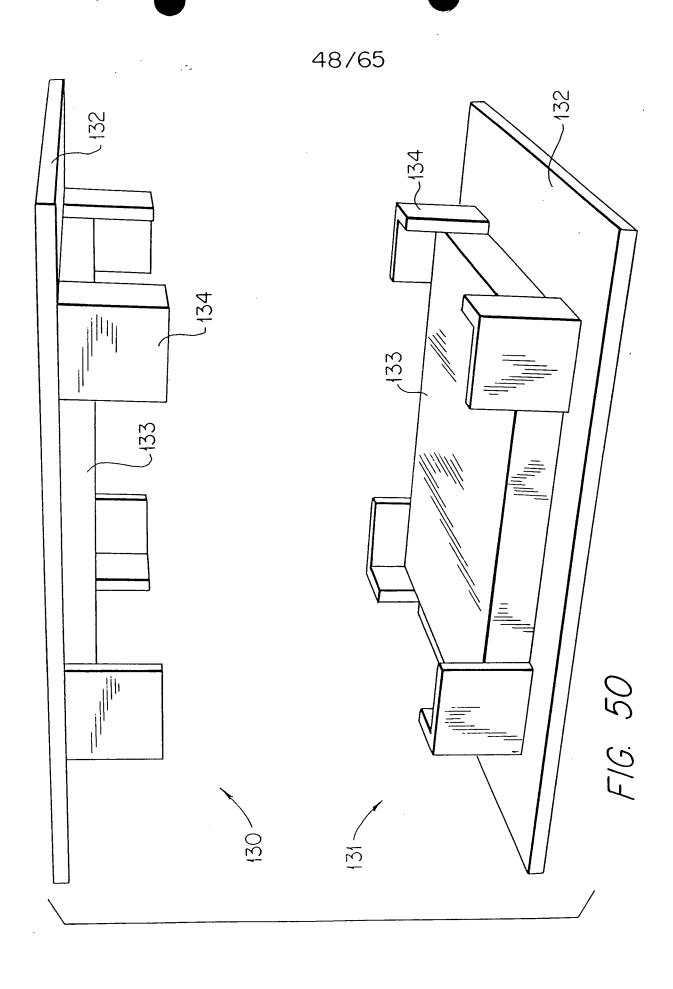


FIG. 47(b)







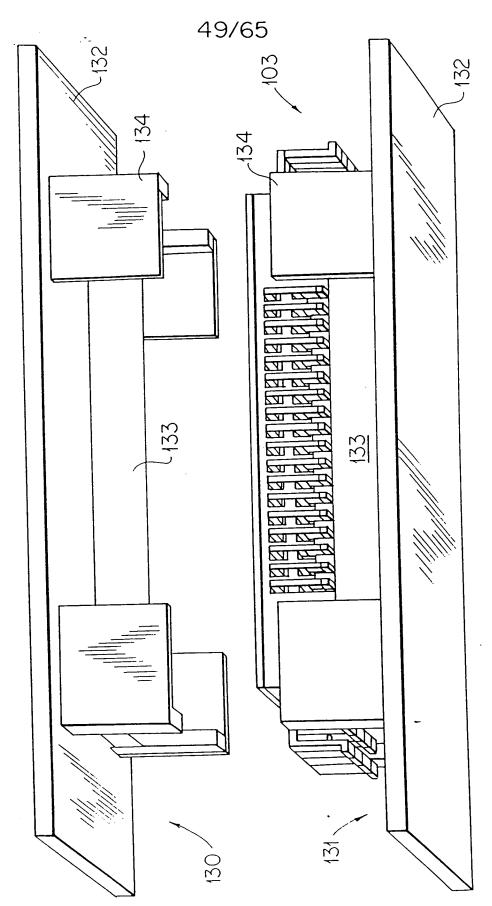
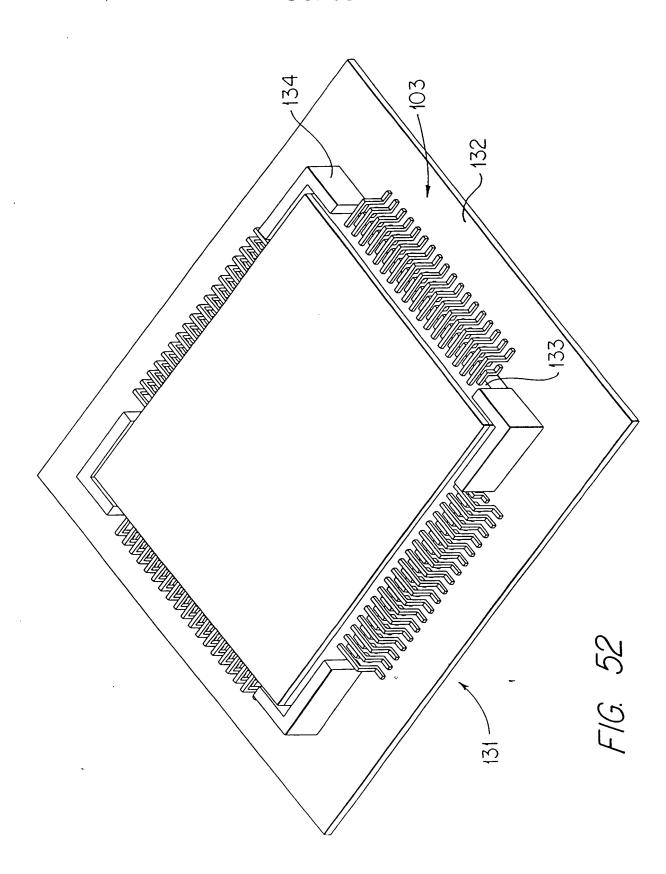
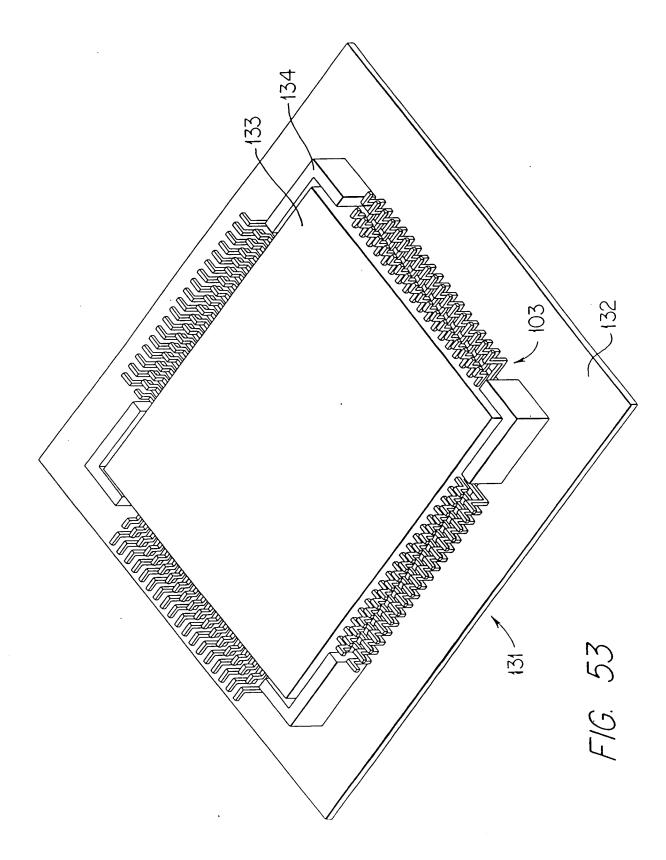
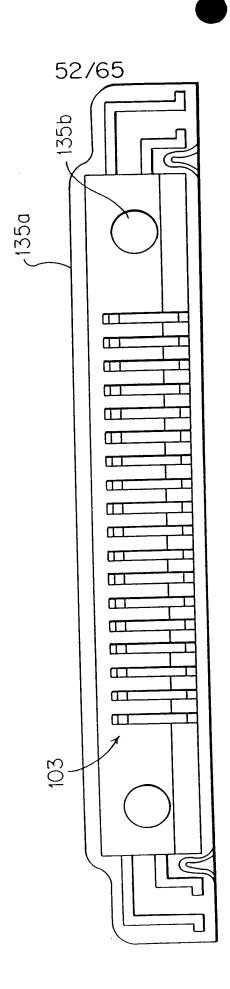


FIG 51

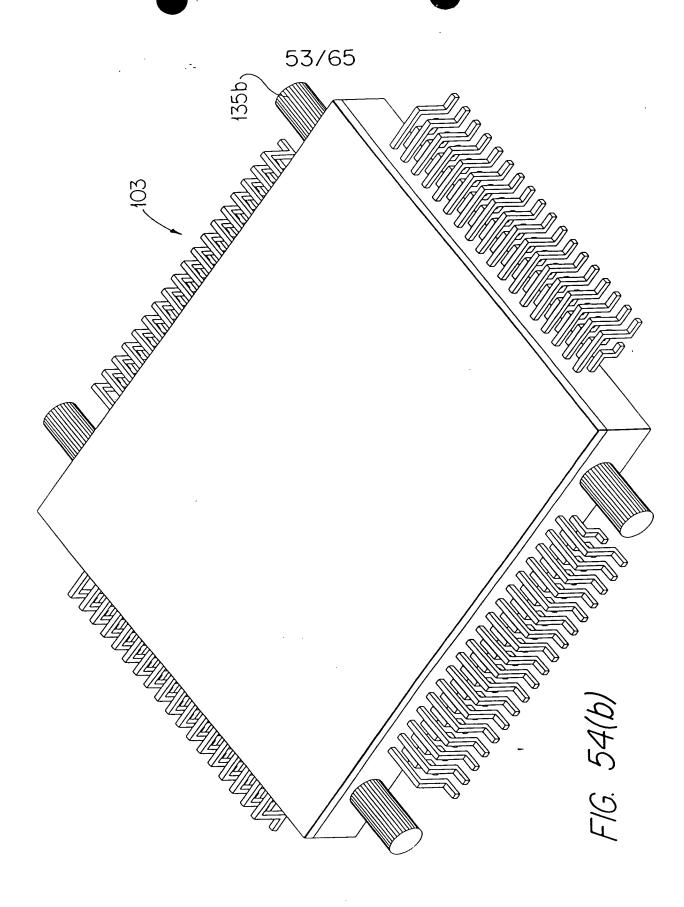
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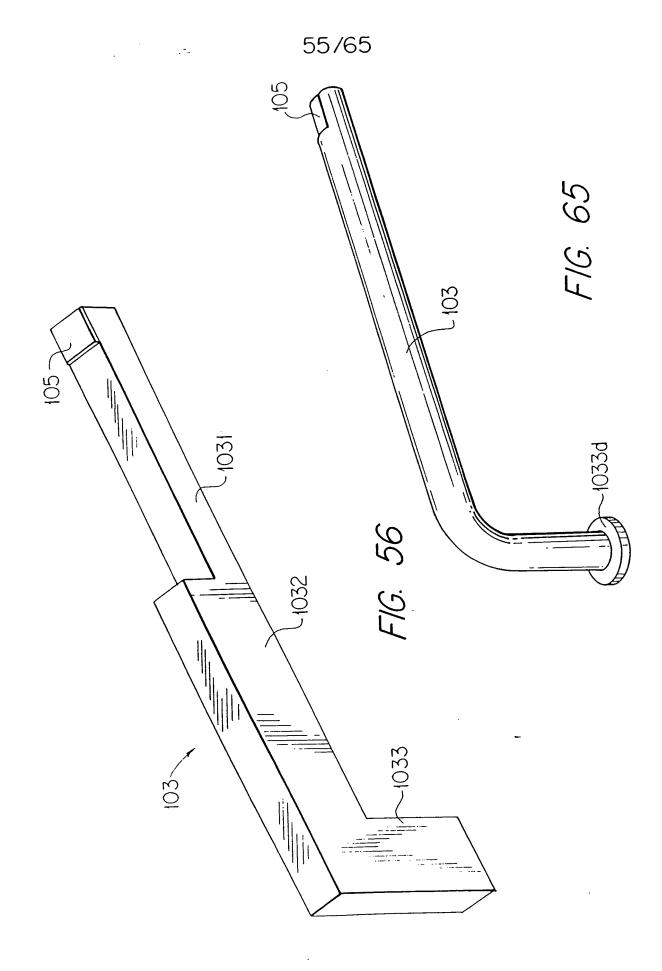






F1G. 54(a)





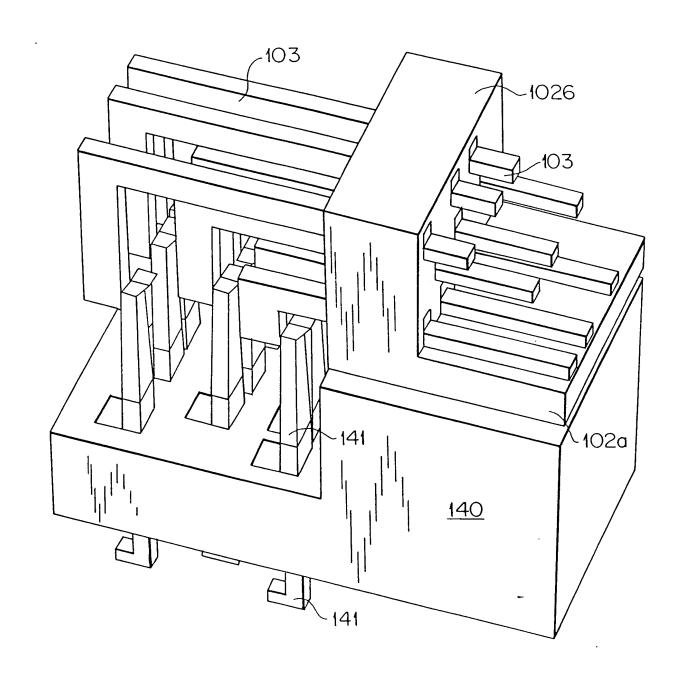
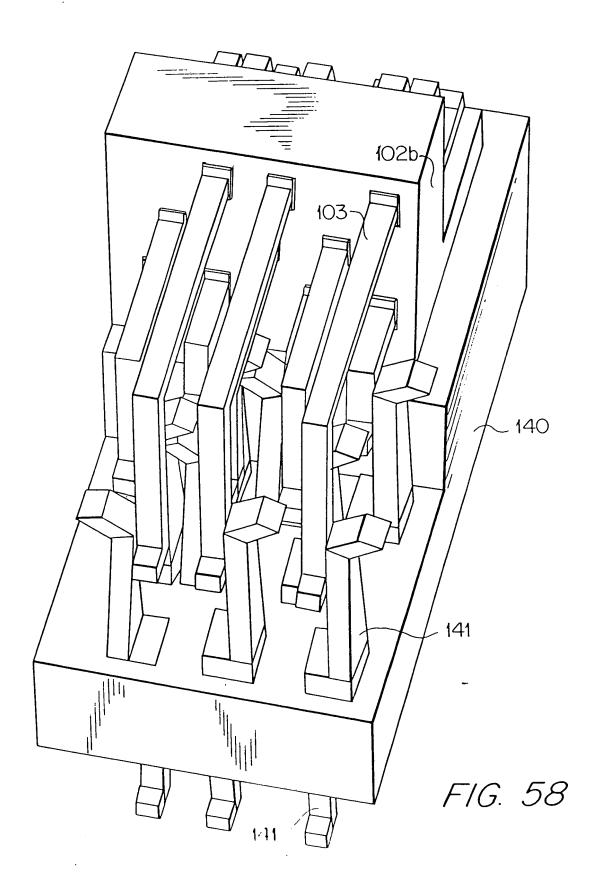


FIG. 57



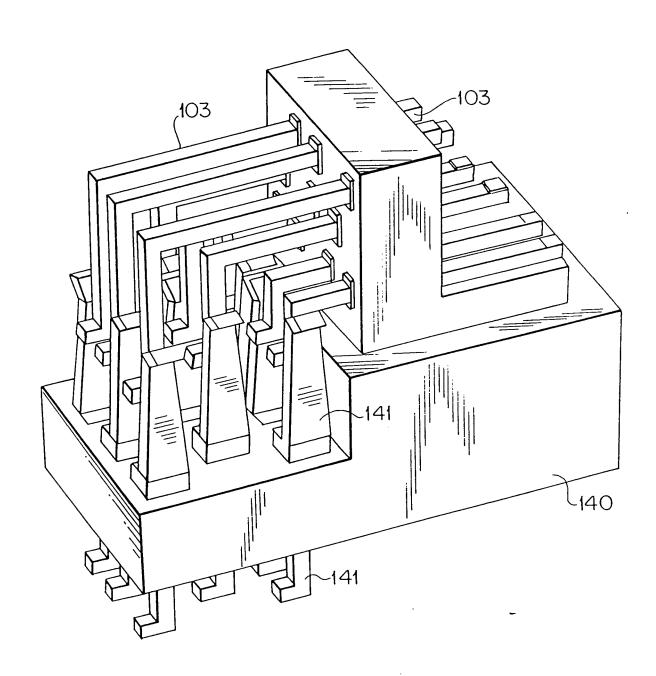
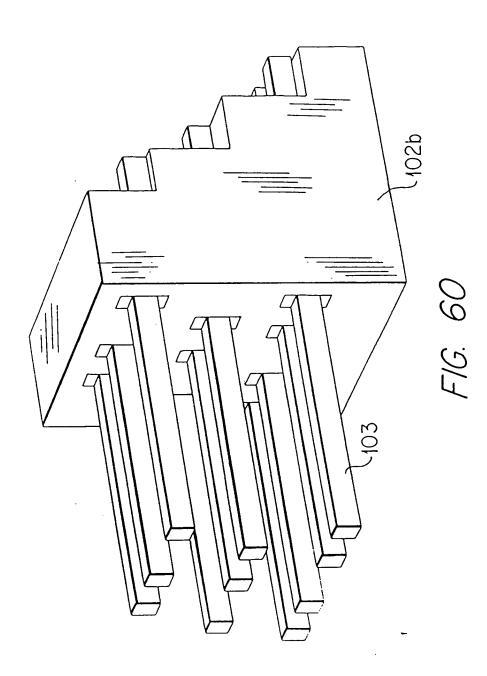
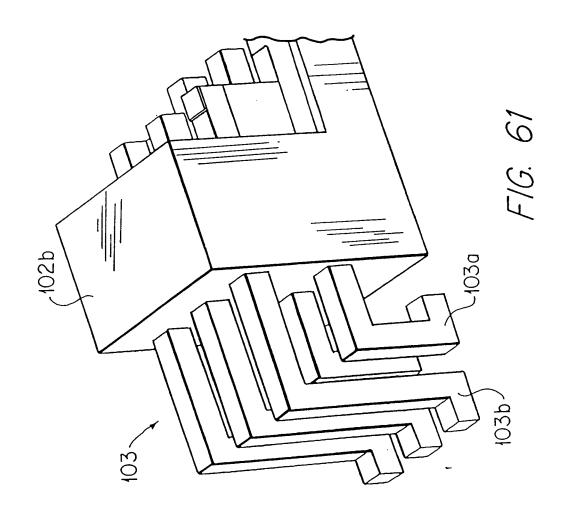
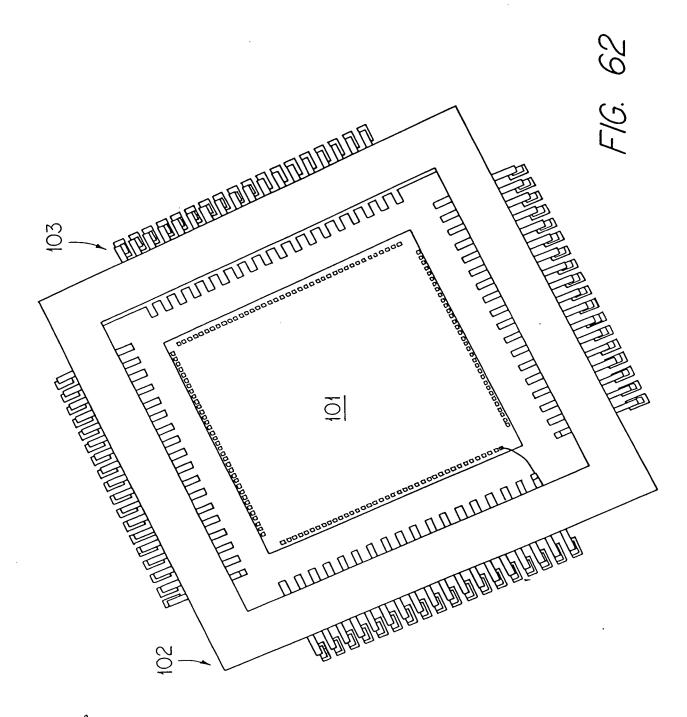


FIG. 59







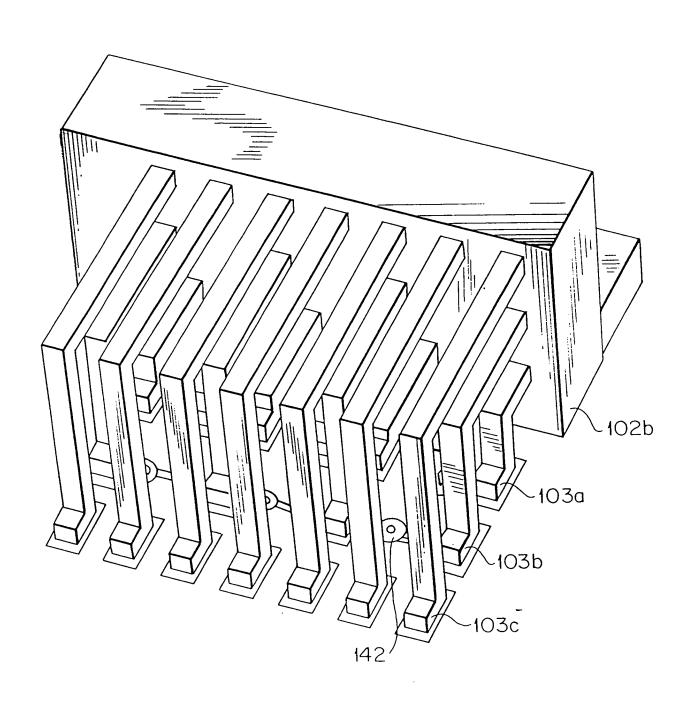


FIG 63

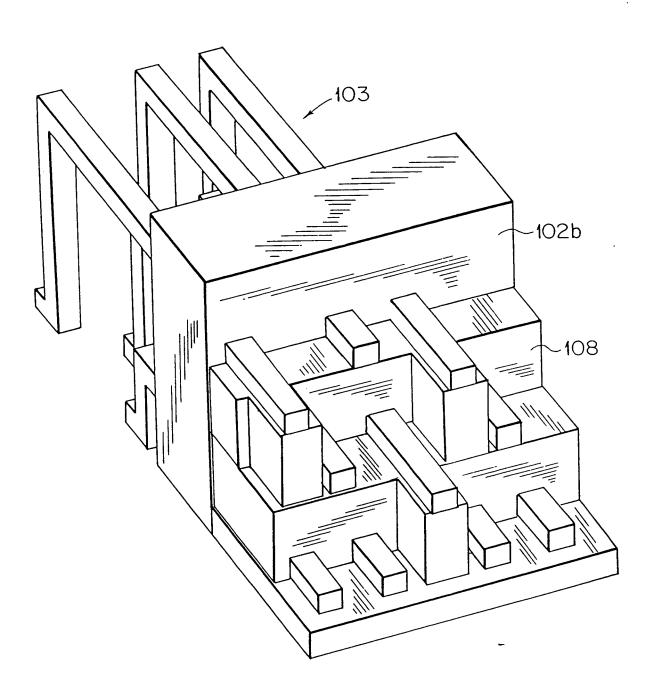


FIG. 64

